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A

B

C

D

E

F

G

H

I

6

V

5

4

WMI

Table of Contents

Page 01 Overview Sheet

Page 02 Block Diagram

Page 03 coupling antenna, NFC, CapSense, NTCs

PCB-Stackup

4M08i200i300V1

Top

9-17µm base Cu *

200 µm FR4

35µm Cu

300 µm FR4

35µm Cu

200 µm FR4

9-17µm base Cu *

Bottom

Tolerance: For each listed base material (Prepreg, Core) acc. to IPC-4101 Class C/M

* Final Copper-thickness (base Cu + plating) acc. to IPC-6012 Class II

The PCB-thickness (over all dimension) is a result of the addition of the multilayer thickness
plus copper plating and plus soldermask = **0.9 mm ± 10%**

Legend:

Functionblock

Line Style = Dot

Solder Pad

Test Point

Spark Gap

Bridge

Diff pair

Trace Impedance

Comments and notes

Line Style = Phantom

EMC-Shielding

Line Style = Big Dash

GND

EP2015/005		Copyright Protection according to DIN 34 / DIN ISO 16016		CAD-CODE: LP1450-5	V1240-305	Page: 1 of 3
Substitute for:		Date	Name	Schematic V1240-305/LP1450-5 WMI02 ANT BR205 DAG		
		Drawn	10.11.17	Bock		
		Check.				
		Viewed				
Revision	Date	Name	Valeo 2189-240-305-00			

Circuit-Diagrams and Component--Placement--Drawings are also available in PDF--Format !!

A

B

C

D

E

F

G

H

I

1

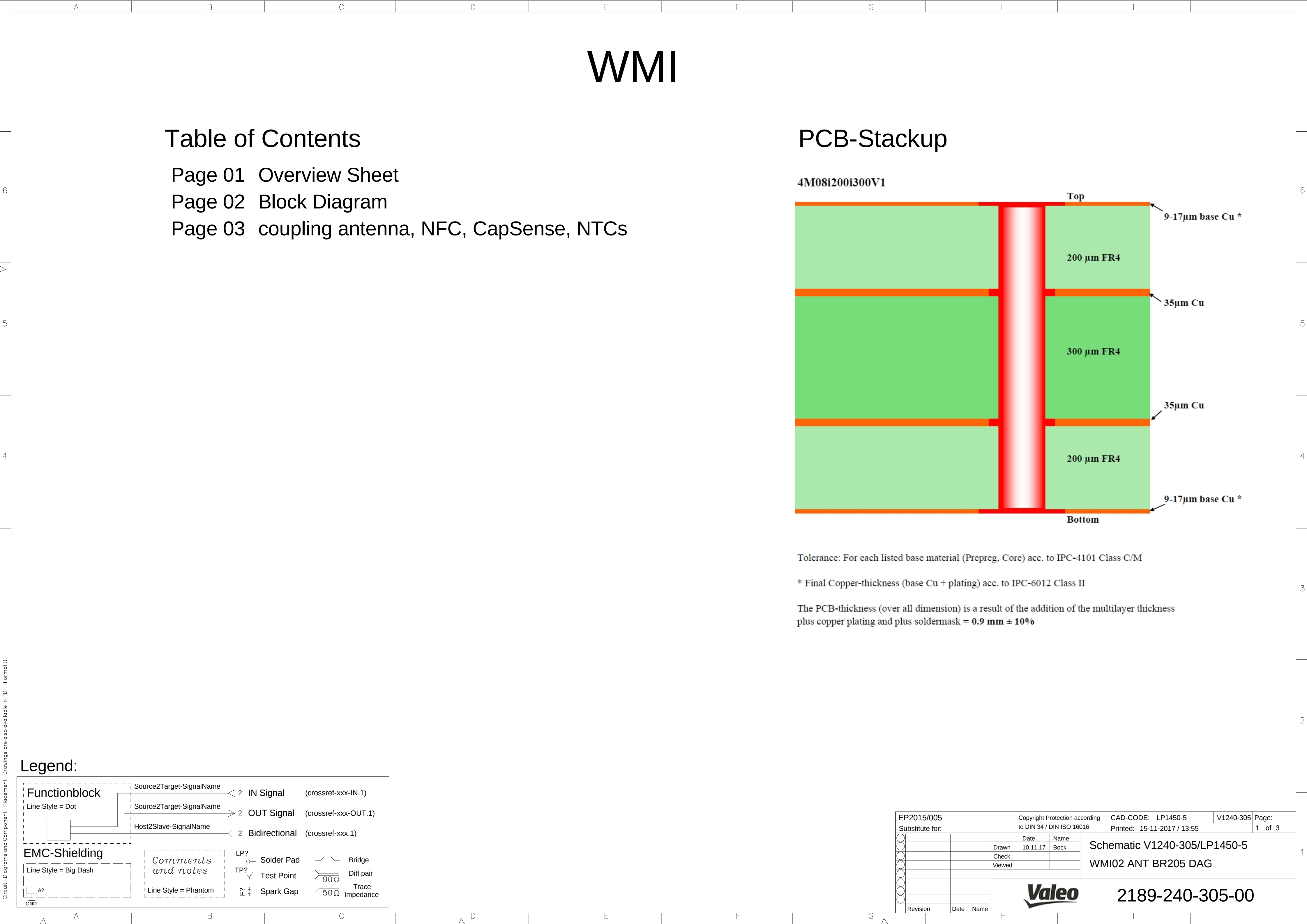
2

3

4

5

6

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A

B

C

D

E

F

G

H

I

6

V

5

4

3

2

1

WMI

Table of Contents

Page 01 Overview Sheet

Page 02 Block Diagram

Page 03 coupling antenna, NFC, CapSense, NTCs

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Legend:

Functionblock

Line Style = Dot

Source2Target-SignalName

< 2 IN Signal (crossref-xxx-IN.1)

Source2Target-SignalName

> 2 OUT Signal (crossref-xxx-OUT.1)

Host2Slave-SignalName

< 2 Bidirectional (crossref-xxx.1)

EMC-Shielding

Line Style = Big Dash

A?

GND

Comments
and notes

Line Style = Phantom

LP? Solder Pad

TP? Test Point

⚡↓↑

Spark Gap

Bridge

Diff pair

Trace Impedance

EP2015/005

Substitute for:

Date

Name

Drawn

Check.

Viewed

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CAD-CODE: LP1450-5 V1240-305

Printed: 15-11-2017 / 13:55

Schematic V1240-305/LP1450-5 WMI02 ANT BR205 DAG

Valeo

2189-240-305-00

Revision

Date

Name

Page:

1 of 3

A

B

C

D

E

F

G

H

I

6

V

5

4

3

2

1

WMI

Table of Contents

Page 01 Overview Sheet

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Page 03 coupling antenna, NFC, CapSense, NTCs

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Host2Slave-SignalName < 2 Bidirectional (crossref-xxx.1)

EMC-Shielding

Line Style = Big Dash

A? GND

Comments and notes

Line Style = Phantom

LP? Solder Pad

TP? Test Point

Spark Gap

Bridge

Diff pair 90Ω

Trace Impedance 50Ω

EP2015/005

Copyright Protection according to DIN 34 / DIN ISO 16016

CAD-CODE: LP1450-5 V1240-305

Date Name

Substitute for:

Printed: 15-11-2017 / 13:55

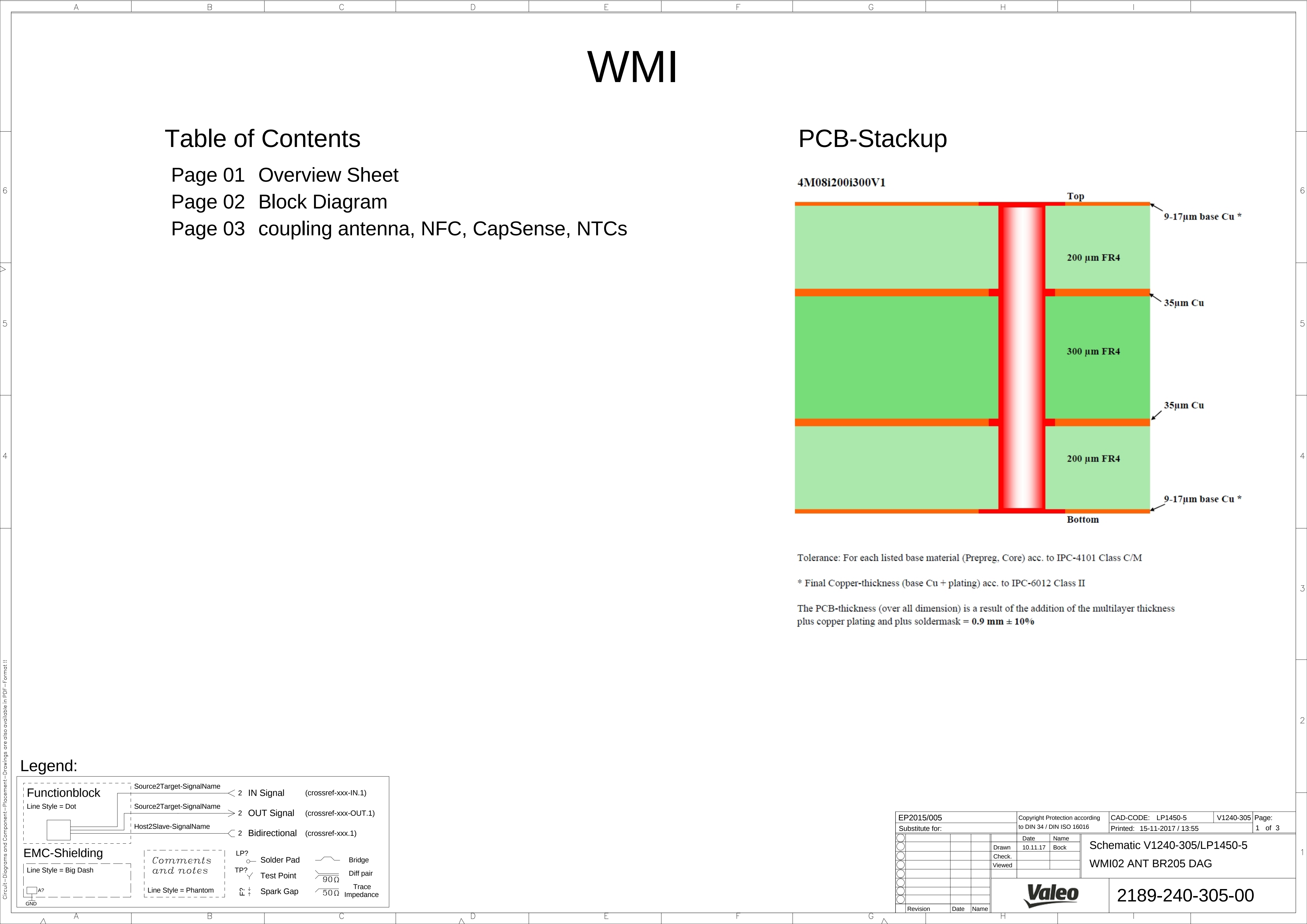
Schematic V1240-305/LP1450-5

WMI02 ANT BR205 DAG

Valeo

2189-240-305-00

Revision Date Name

[illegible]

A

B

C

D

E

F

G

H

I

6

V

5

4

WMI

Table of Contents

Page 01 Overview Sheet

Page 02 Block Diagram

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A? GND

Comments and notes

Line Style = Phantom

LP? Solder Pad

TP? Test Point

Spark Gap

Bridge

Diff pair 90Ω

Trace Impedance 50Ω

EP2015/005

Copyright Protection according to DIN 34 / DIN ISO 16016

CAD-CODE: LP1450-5 V1240-305

Printed: 15-11-2017 / 13:55

Date Name

Drawn 10.11.17 Bock

Check.

Viewed

Schematic V1240-305/LP1450-5 WMI02 ANT BR205 DAG

Valeo

2189-240-305-00

Revision Date Name

Substitute for:

1 of 3

A

B

C

D

E

F

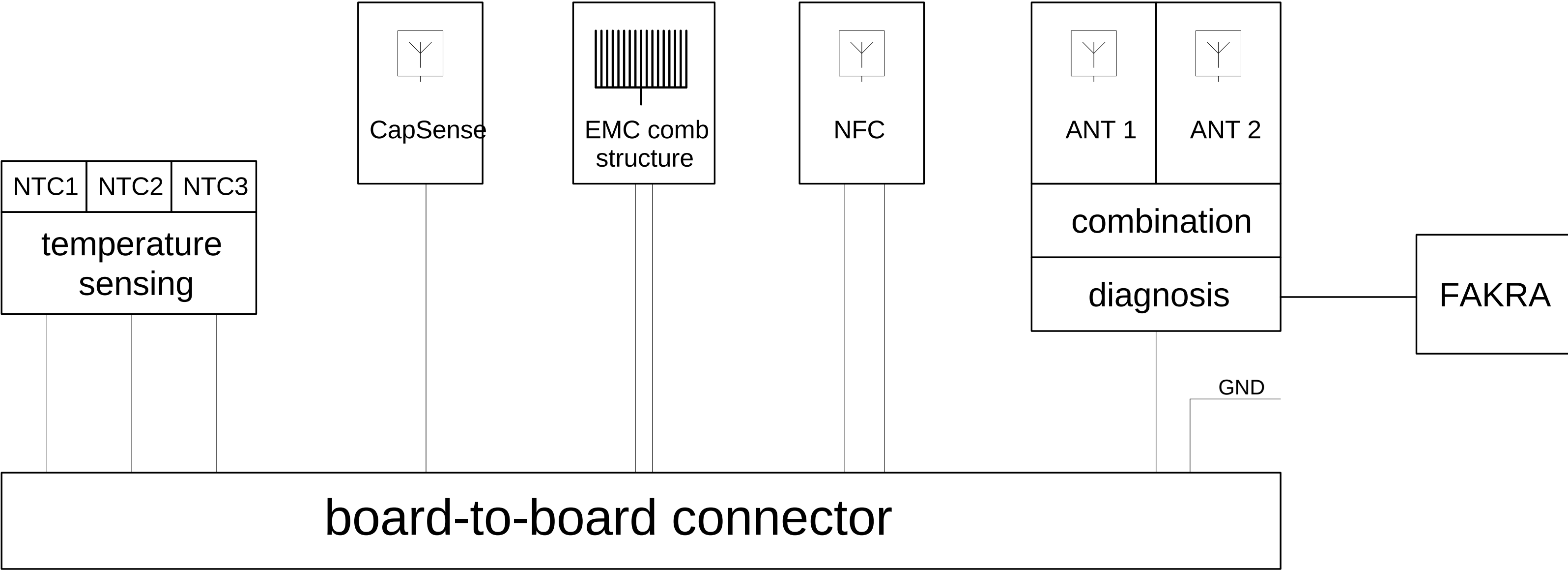
G

H

I

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Block Diagram



EP2015/005				Copyright Protection according to DIN 34 / DIN ISO 16016		CAD-CODE: LP1450-5		V1240-305	Page:
Substitute for:						Printed: 15-11-2017 / 13:55		2 of 3	
☐				Date	Name	Schematic V1240-305/LP1450-5 WMI02 ANT BR205 DAG			
☐				Drawn	10.11.17 Bock				
☐				Check.	see page 1				
☐				Viewed	see page 1				
☐									
☐									
☐									
Revision		Date	Name			2189-240-305-00			

